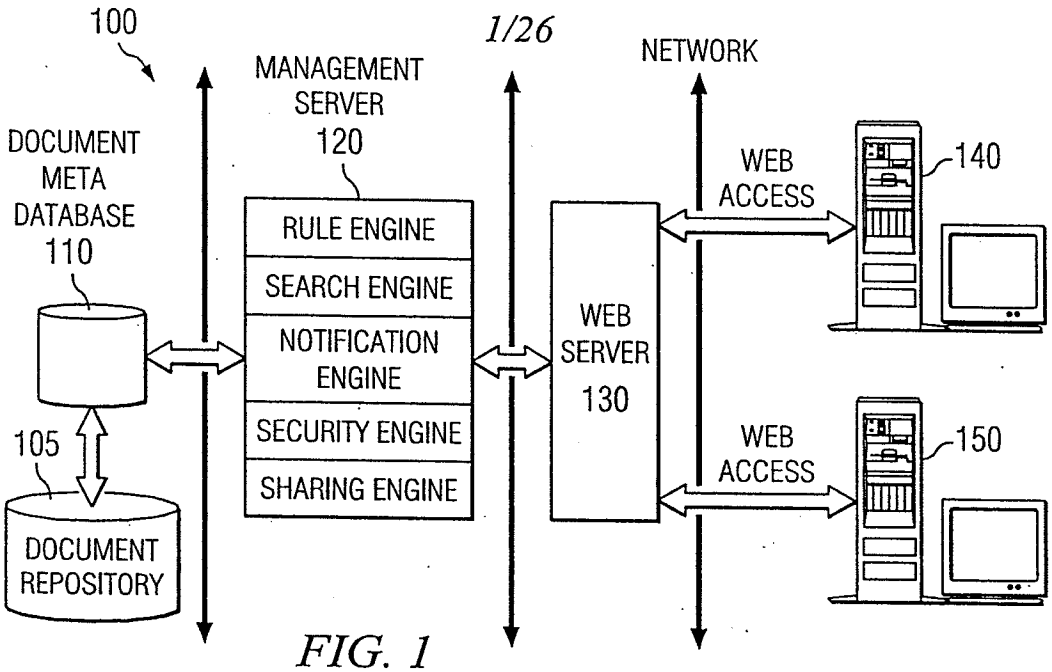

100
MANAGEMENT SERVER
120
NETWORK
DOCUMENT META DATABASE
110
RULE ENGINE
SEARCH ENGINE
NOTIFICATION ENGINE
SECURITY ENGINE
SHARING ENGINE
WEB SERVER
130
WEB ACCESS
140
WEB ACCESS
150
105
DOCUMENT REPOSITORY

FIG. 1

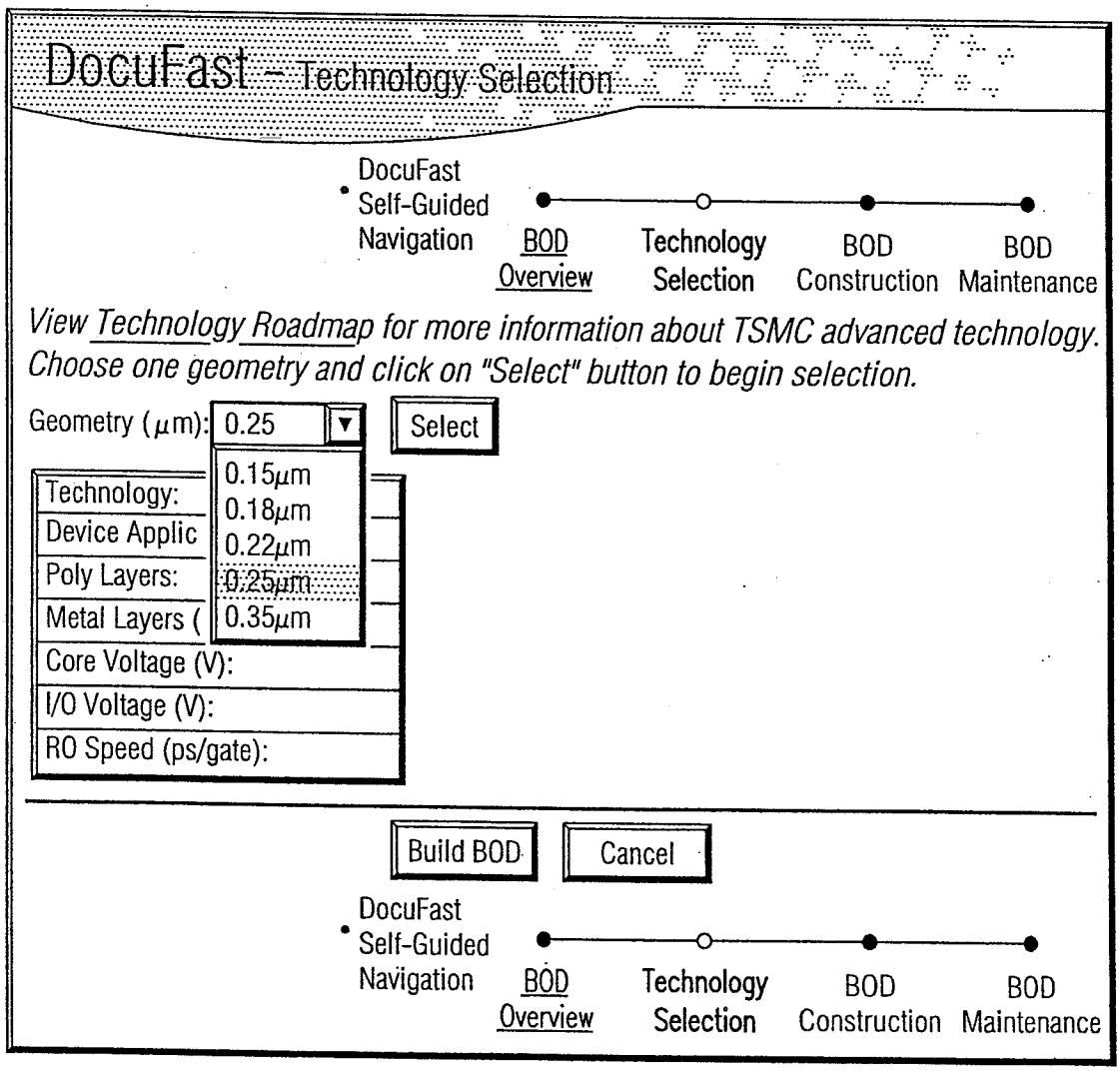

DocuFast – Technology Selection
DocuFast Self-Guided Navigation
BOD Overview
Technology Selection
BOD Construction
BOD Maintenance
View Technology Roadmap for more information about TSMC advanced technology.
Choose one geometry and click on "Select" button to begin selection.
Geometry (μm): 0.25
Select
0.15μm
0.18μm
0.22μm
0.25μm
0.35μm
Technology:
Device Applic
Poly Layers:
Metal Layers (
Core Voltage (V):
I/O Voltage (V):
RO Speed (ps/gate):
Build BOD
Cancel
DocuFast Self-Guided Navigation
BOD Overview
Technology Selection
BOD Construction
BOD Maintenance

FIG. 2A

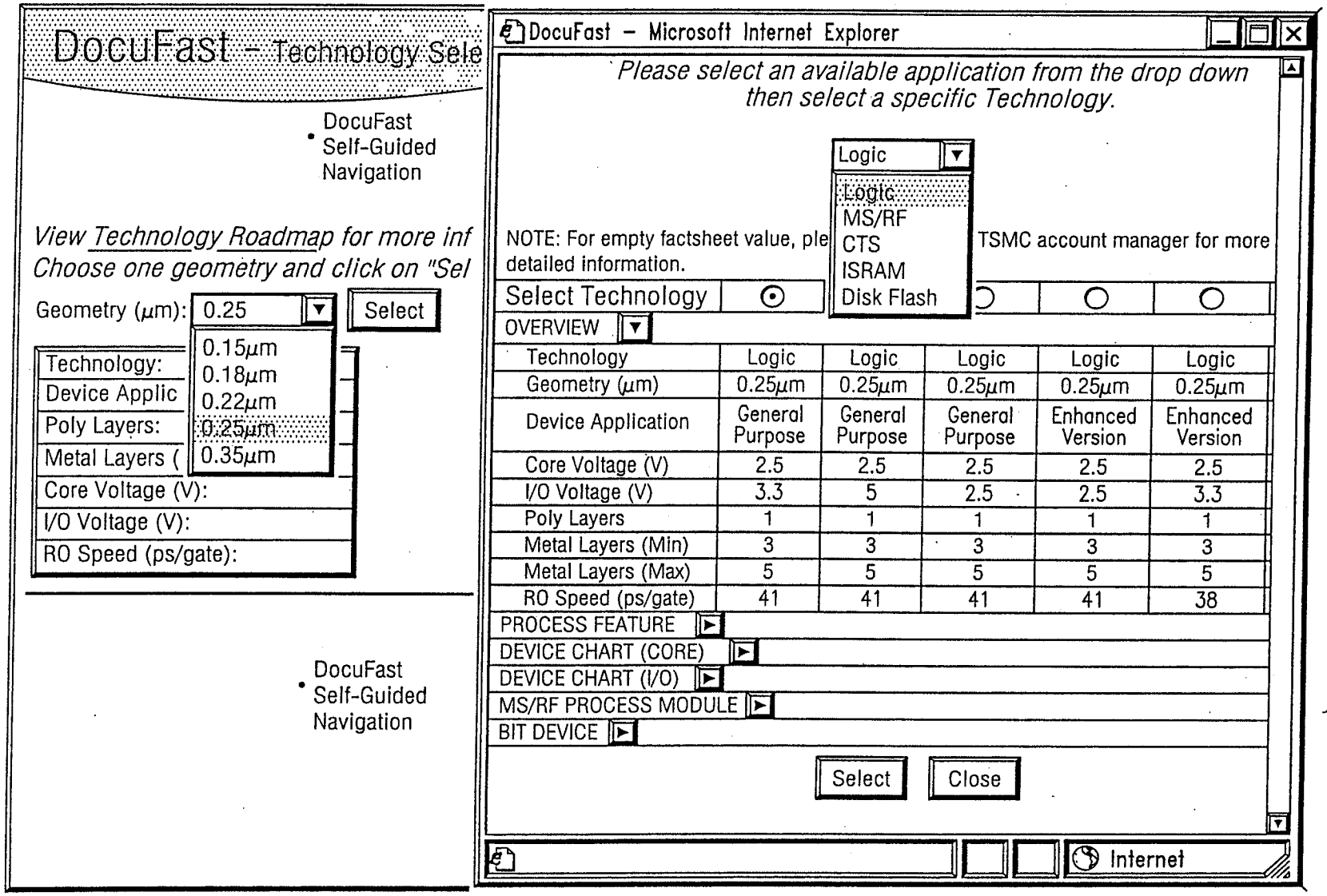

DocuFast – Technology Sele
DocuFast Self-Guided Navigation
View Technology Roadmap for more inf
Choose one geometry and click on "Sel
Geometry (μm): 0.25
Select
0.15μm
0.18μm
0.22μm
0.25μm
0.35μm
Technology:
Device Applic
Poly Layers:
Metal Layers (
Core Voltage (V):
I/O Voltage (V):
RO Speed (ps/gate):
DocuFast Self-Guided Navigation
DocuFast – Microsoft Internet Explorer
Please select an available application from the drop down then select a specific Technology.
Logic
Logic
MS/RF
CTS
ISRAM
Disk Flash
NOTE: For empty factsheet value, ple
detailed information.
TSMC account manager for more
Select Technology
OVERVIEW
Technology | Logic | Logic | Logic | Logic | Logic
Geometry (μm) | 0.25μm | 0.25μm | 0.25μm | 0.25μm | 0.25μm
Device Application | General Purpose | General Purpose | General Purpose | Enhanced Version | Enhanced Version
Core Voltage (V) | 2.5 | 2.5 | 2.5 | 2.5 | 2.5
I/O Voltage (V) | 3.3 | 5 | 2.5 | 2.5 | 3.3
Poly Layers | 1 | 1 | 1 | 1 | 1
Metal Layers (Min) | 3 | 3 | 3 | 3 | 3
Metal Layers (Max) | 5 | 5 | 5 | 5 | 5
RO Speed (ps/gate) | 41 | 41 | 41 | 41 | 38
PROCESS FEATURE
DEVICE CHART (CORE)
DEVICE CHART (I/O)
MS/RF PROCESS MODULE
BIT DEVICE
Select
Close
Internet

FIG. 2B

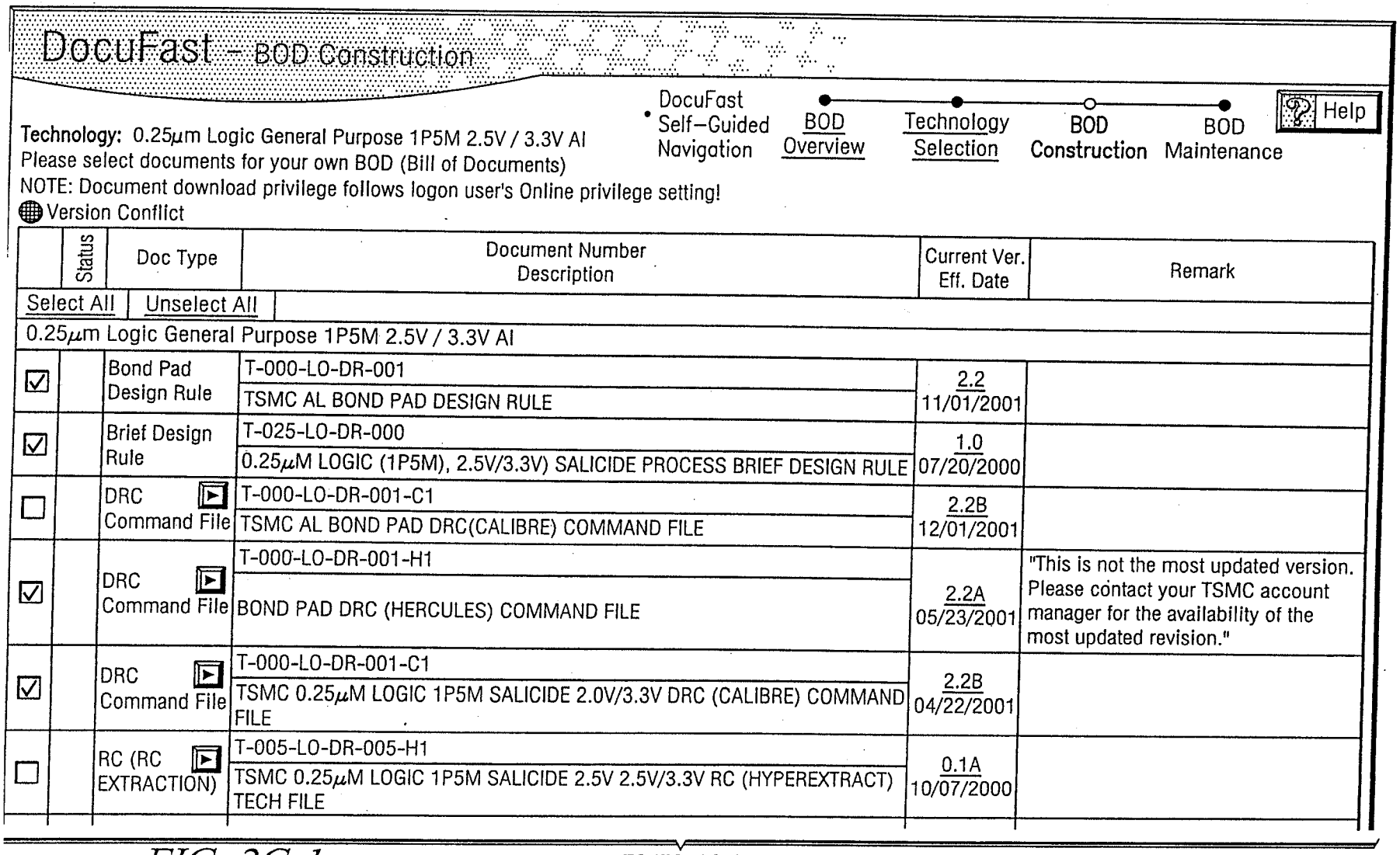


FIG. 2C-1

TO FIG. 2C-2

FROM FIG. 2C-1

☐		RC (RC EXTRACTION)	T-025-LO-SP-005-Q1 TSMC 0.25μM LOGIC 1P5M SALICIDE 2.5V/3.3V RC (COLUMBUS) TECH FILE (3RD PARTY)	1.00 01/17/2001	*NOTE*
☐		RC (RC EXTRACTION)	T-025-LO-SP-005-R1 TSMC 0.25μM LOGIC 1P8M SALICIDE 3.5V, 2.5V/3.3V RC (RAPHAEL NEC) TECH FILE	1.0A 07/20/2000	
☐		RC (RC EXTRACTION)	T-025-LO-SP-005-S1 TSMC 0.25μM LOGIC 1P5M SALICIDE 2.5V, 2.5V/3.3V RC (STAR-RC) TECH FILE	2.1A 10/07/2000	
☑		RC (RC EXTRACTION)	T-025-LO-SP-005-X1 TSMC 0.25μM LOGIC 1P5M SALICIDE 2.5V, 2.5V/3.3V RC (XCALIBRE) TECH FILE	2.1A 10/07/2000	
☑		SPICE Models	T-025-LO-SP-001 TSMC 0.25μM LOGIC 1P4M SALICIDE 2.5V, 2.5V/3.3V SPICE MODELS (WITH 3 DISK)	1.4 07/30/2000	
☐		SPICE Models	T-025-LO-SP-002 TSMC 0.25μM LOGIC 1P3M SALICIDE 2.5V, 2.5V/3.3V SPICE MODELS (WITH 2 DISK)	1.4 07/30/2000	
☐		SPICE Models	T-025-LO-SP-003 TSMC 0.25μM LOGIC 1P4M SALICIDE 2.5V, 2.5V/3.3V SPICE MODELS (WITH 1 DISK)	2.2 02/26/2002	

Select All | Unselect All

Add to BOD | Cancel

DocuFast Self-Guided Navigation: BOD Overview — Technology Selection — BOD Construction — BOD Maintenance

4/26

FIG. 2C-2

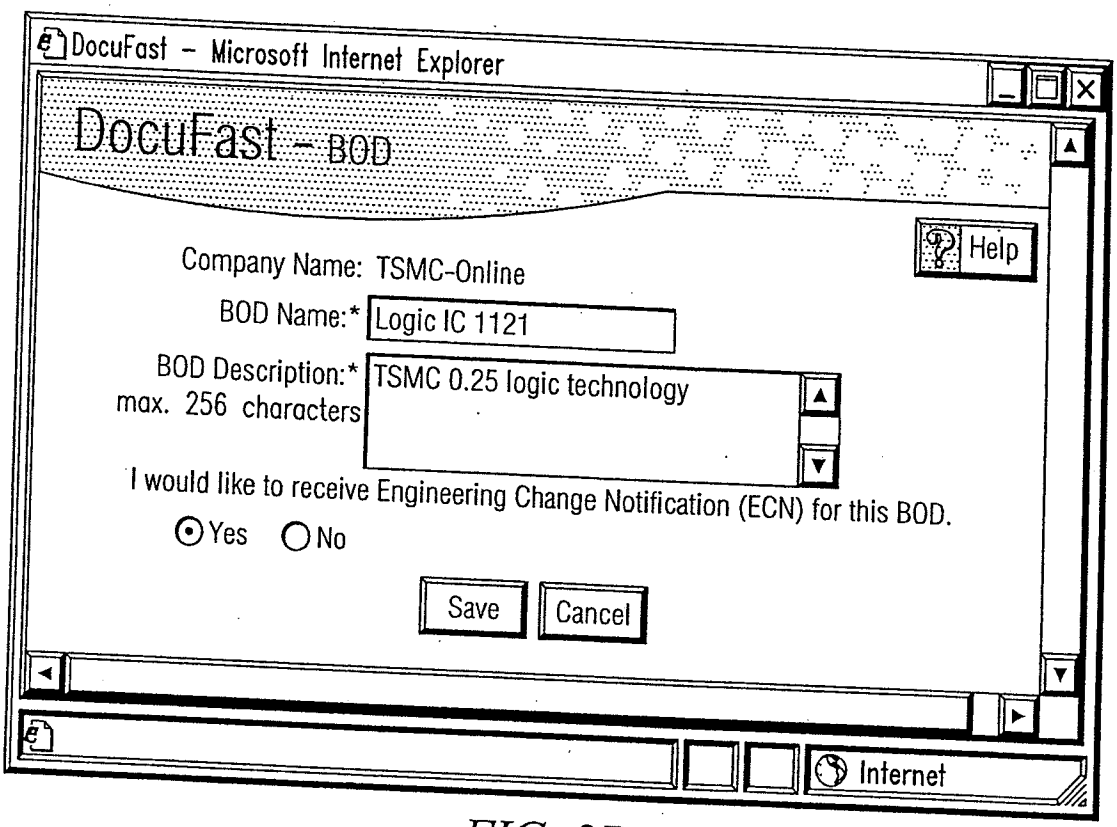

DocuFast - Microsoft Internet Explorer
DocuFast - BOD
Help
Company Name: TSMC-Online
BOD Name:*
Logic IC 1121
BOD Description:*
max. 256 characters
TSMC 0.25 logic technology
I would like to receive Engineering Change Notification (ECN) for this BOD.
Yes
No
Save
Cancel
Internet

FIG. 2D

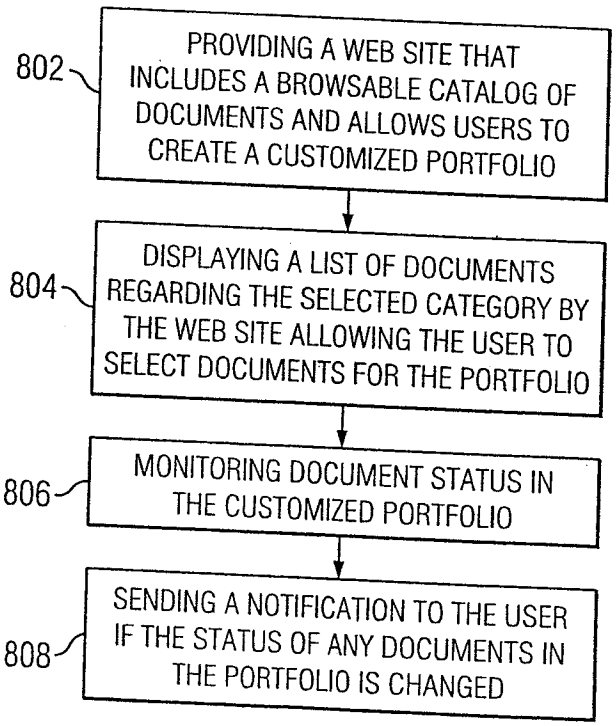

802
PROVIDING A WEB SITE THAT INCLUDES A BROWSABLE CATALOG OF DOCUMENTS AND ALLOWS USERS TO CREATE A CUSTOMIZED PORTFOLIO
804
DISPLAYING A LIST OF DOCUMENTS REGARDING THE SELECTED CATEGORY BY THE WEB SITE ALLOWING THE USER TO SELECT DOCUMENTS FOR THE PORTFOLIO
806
MONITORING DOCUMENT STATUS IN THE CUSTOMIZED PORTFOLIO
808
SENDING A NOTIFICATION TO THE USER IF THE STATUS OF ANY DOCUMENTS IN THE PORTFOLIO IS CHANGED

FIG. 8

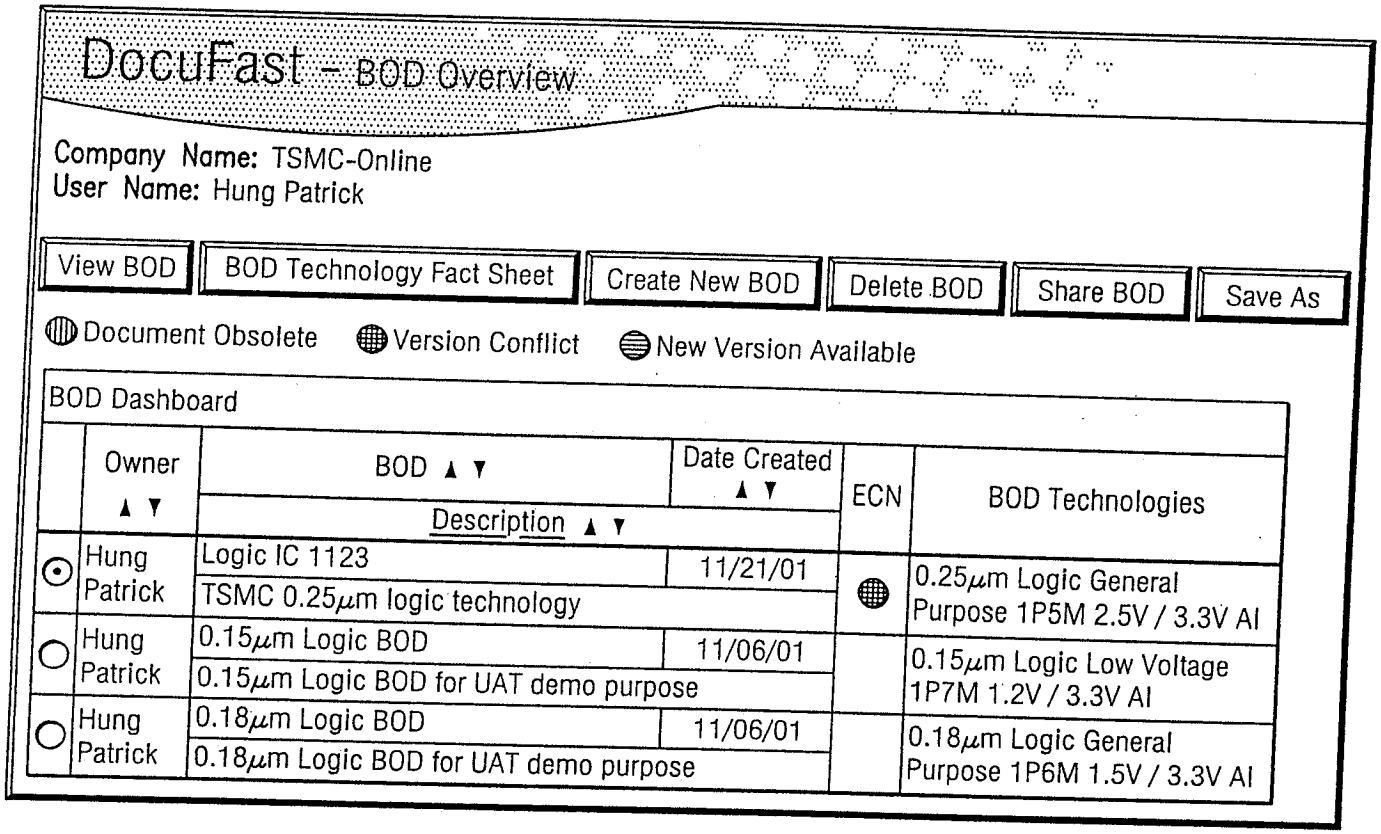

DocuFast - BOD Overview
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BOD Technology Fact Sheet
Create New BOD
Delete BOD
Share BOD
Save As
Document Obsolete
Version Conflict
New Version Available
BOD Dashboard
Owner
BOD
Date Created
ECN
BOD Technologies
Description
Hung Patrick
Logic IC 1123
11/21/01
TSMC 0.25μm logic technology
0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AI
Hung Patrick
0.15μm Logic BOD
11/06/01
0.15μm Logic BOD for UAT demo purpose
0.15μm Logic Low Voltage 1P7M 1.2V / 3.3V AI
Hung Patrick
0.18μm Logic BOD
11/06/01
0.18μm Logic BOD for UAT demo purpose
0.18μm Logic General Purpose 1P6M 1.5V / 3.3V AI

FIG. 2E

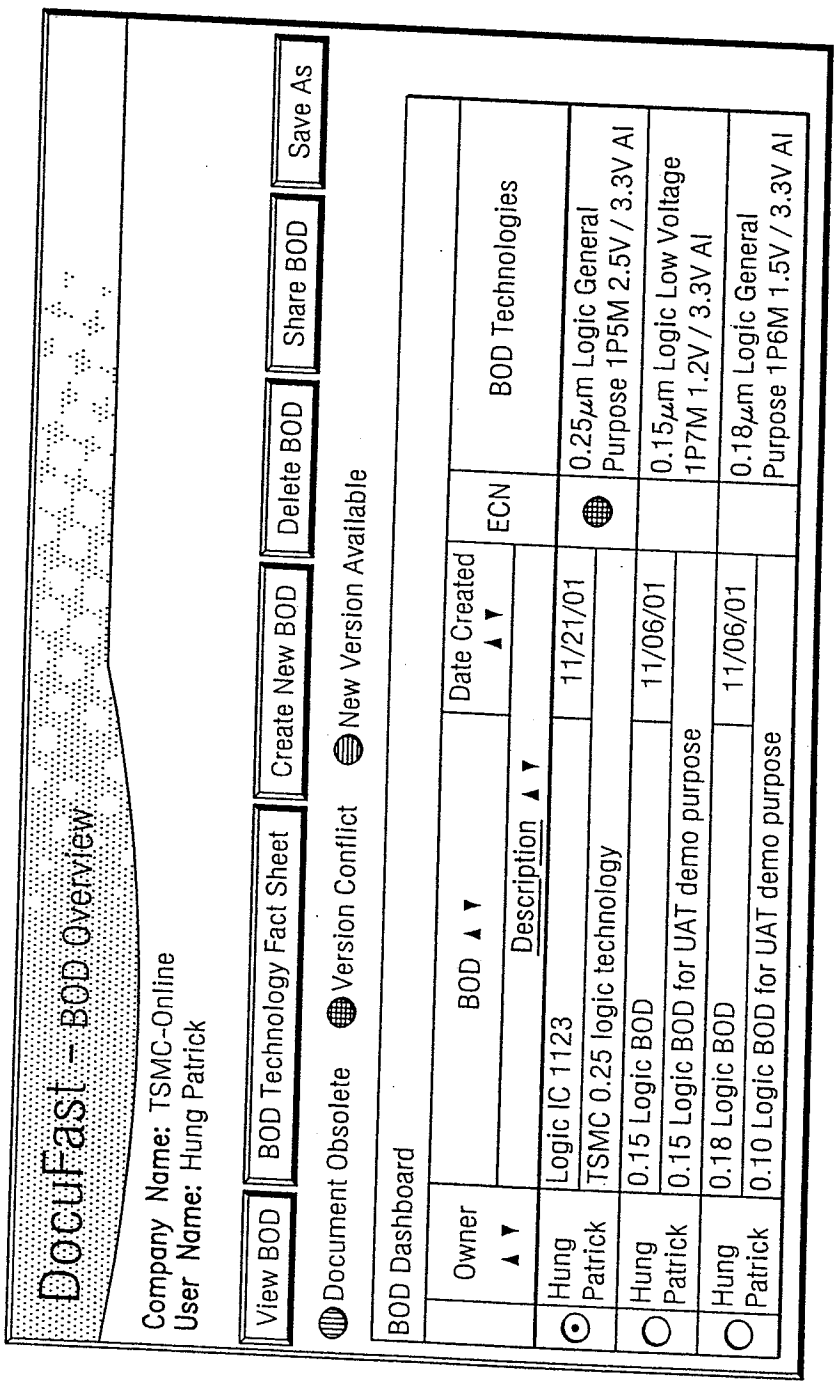

DocuFast - BOD Overview
Company Name: TSMC-Online
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Save As
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Version Conflict
New Version Available
BOD Dashboard
Owner
BOD
Description
Date Created
ECN
BOD Technologies
Hung Patrick
Logic IC 1123
TSMC 0.25 logic technology
11/21/01
0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AI
Hung Patrick
0.15 Logic BOD
0.15 Logic BOD for UAT demo purpose
11/06/01
0.15μm Logic Low Voltage 1P7M 1.2V / 3.3V AI
Hung Patrick
0.18 Logic BOD
0.10 Logic BOD for UAT demo purpose
11/06/01
0.18μm Logic General Purpose 1P6M 1.5V / 3.3V AI

FIG. 3A

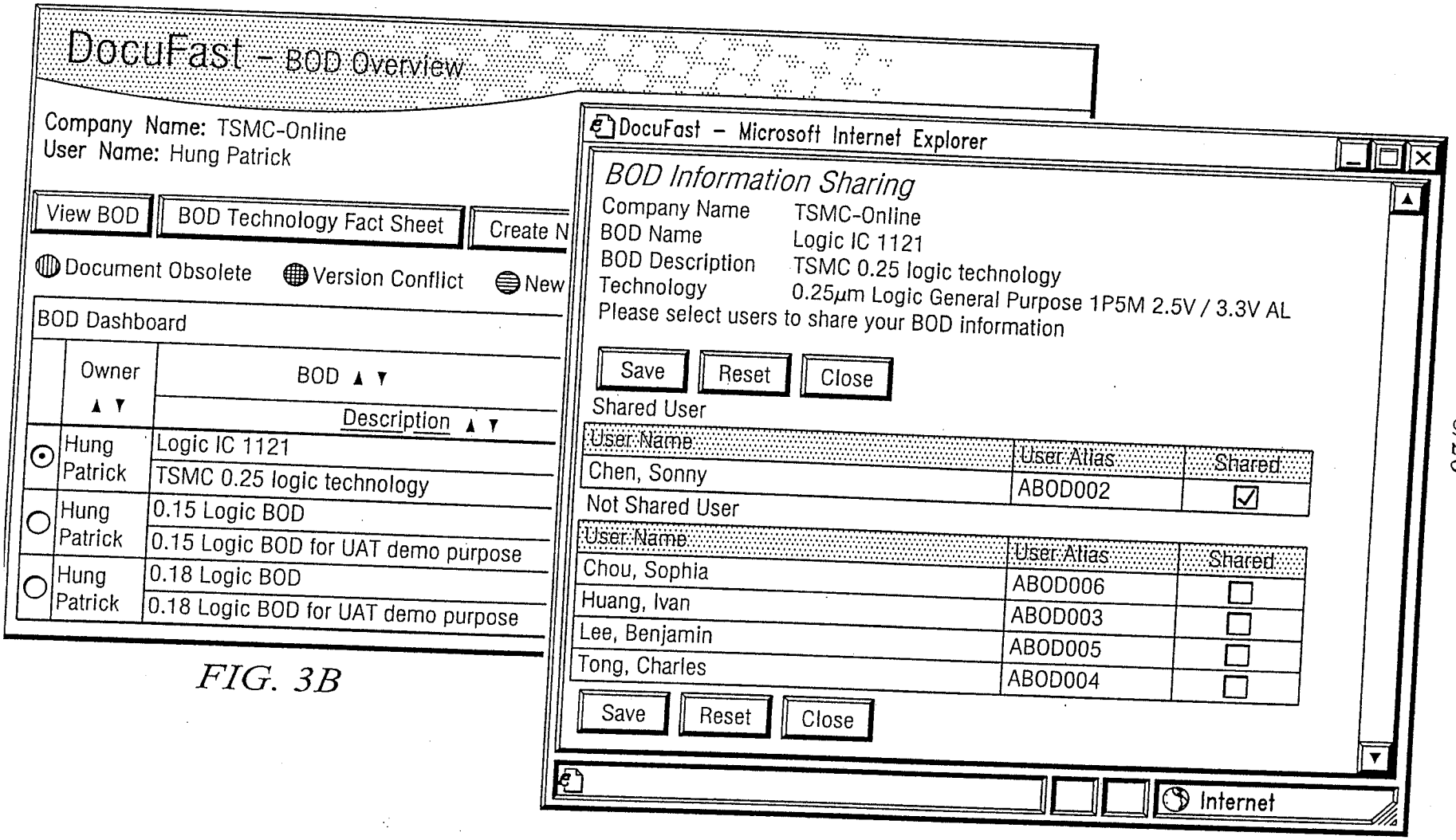

DocuFast - BOD Overview
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User Name: Hung Patrick
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BOD Technology Fact Sheet
Create N
Document Obsolete
Version Conflict
New
BOD Dashboard
Owner
BOD
Description
Hung Patrick
Logic IC 1121
TSMC 0.25 logic technology
Hung Patrick
0.15 Logic BOD
0.15 Logic BOD for UAT demo purpose
Hung Patrick
0.18 Logic BOD
0.18 Logic BOD for UAT demo purpose
DocuFast - Microsoft Internet Explorer
BOD Information Sharing
Company Name TSMC-Online
BOD Name Logic IC 1121
BOD Description TSMC 0.25 logic technology
Technology 0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AL
Please select users to share your BOD information
Save
Reset
Close
Shared User
User Name
User Alias
Shared
Chen, Sonny
ABOD002
Not Shared User
User Name
User Alias
Shared
Chou, Sophia
ABOD006
Huang, Ivan
ABOD003
Lee, Benjamin
ABOD005
Tong, Charles
ABOD004
Save
Reset
Close
Internet

FIG. 3B

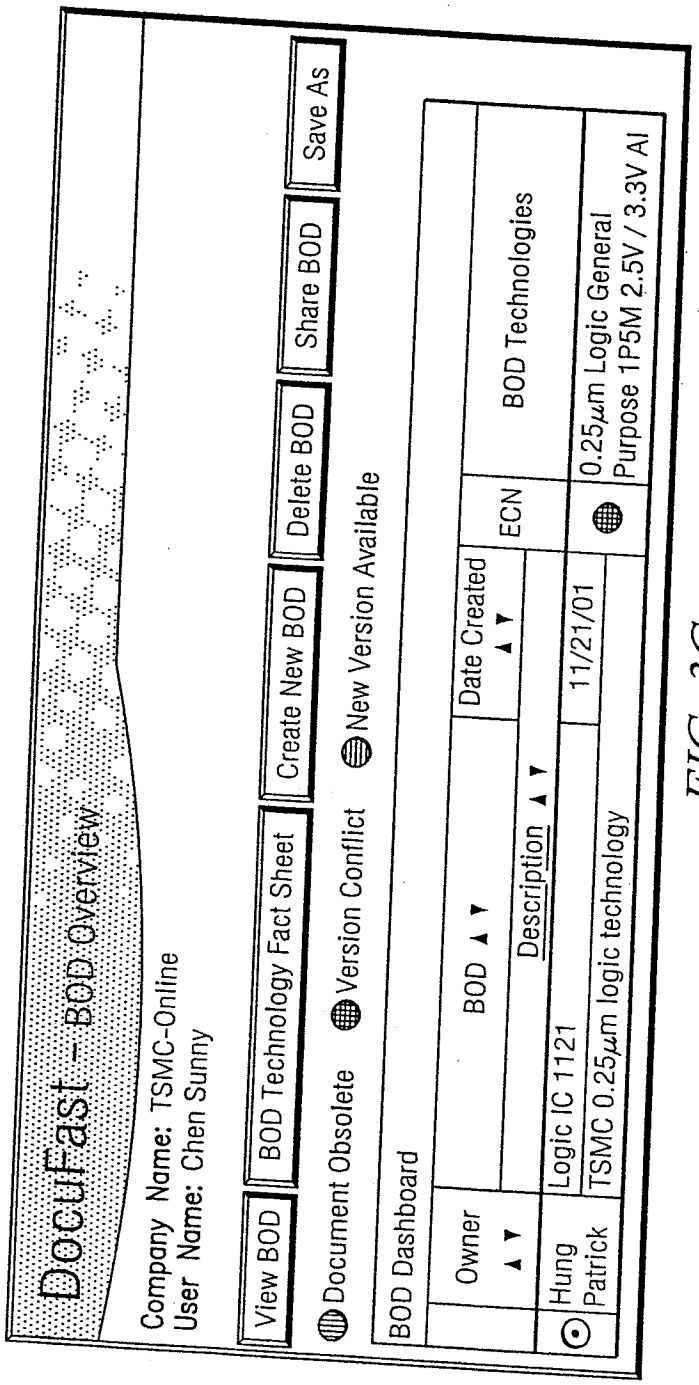

DocuFast – BOD Overview
Company Name: TSMC-Online
User Name: Chen Sunny
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BOD Technology Fact Sheet
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Share BOD
Save As
Document Obsolete
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New Version Available
BOD Dashboard
Owner
BOD
Date Created
ECN
BOD Technologies
Description
Hung Patrick
Logic IC 1121
11/21/01
0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AI
TSMC 0.25μm logic technology

FIG. 3C

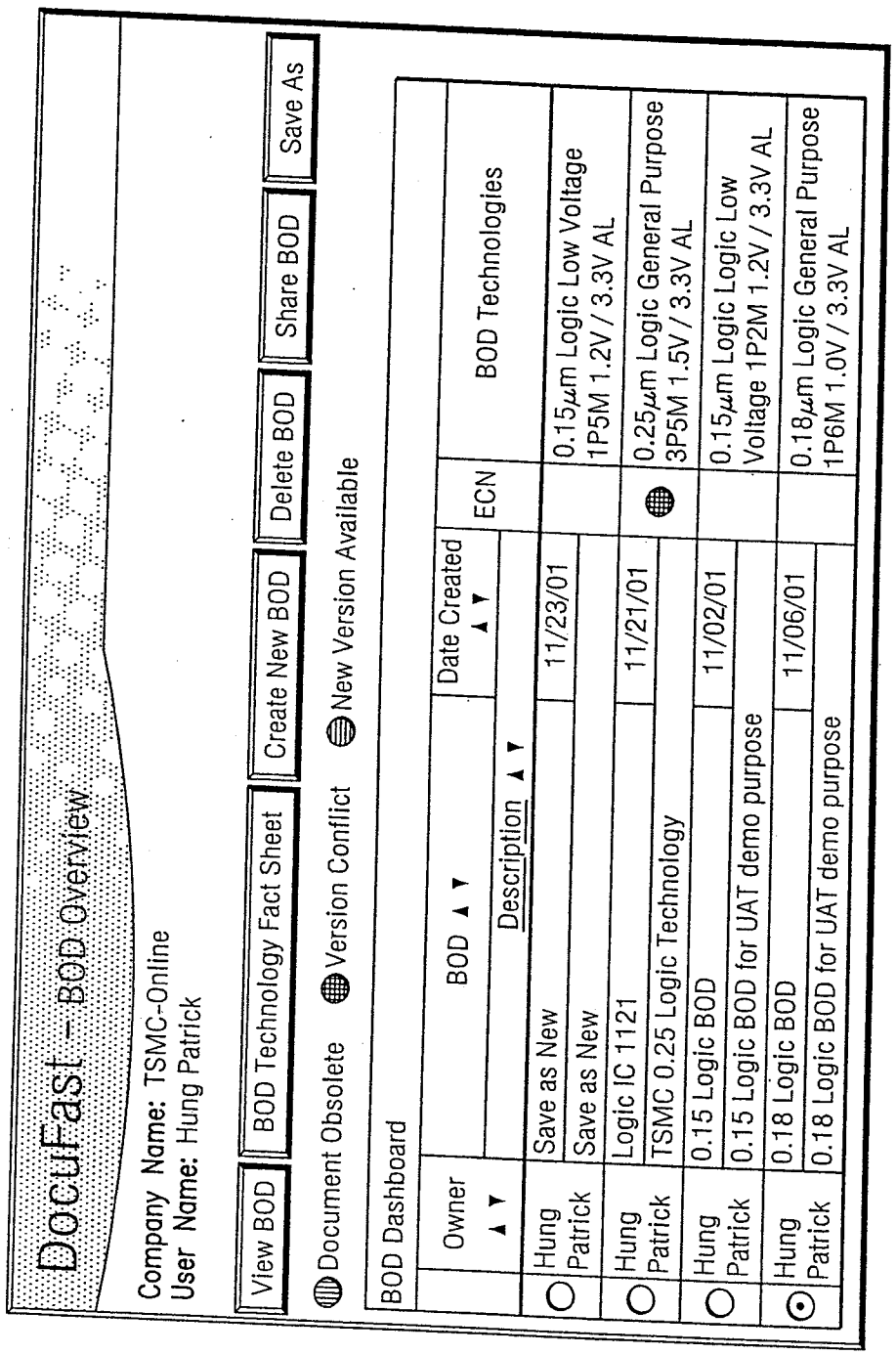

DocuFast - BOD Overview
Company Name: TSMC-Online
User Name: Hung Patrick
View BOD
BOD Technology Fact Sheet
Create New BOD
Delete BOD
Share BOD
Save As
Document Obsolete
Version Conflict
New Version Available
BOD Dashboard
Owner
BOD
Description
Date Created
ECN
BOD Technologies
Hung Patrick
Save as New
11/23/01
0.15μm Logic Low Voltage 1P5M 1.2V / 3.3V AL
Hung Patrick
Logic IC 1121
TSMC 0.25 Logic Technology
11/21/01
0.25μm Logic General Purpose 3P5M 1.5V / 3.3V AL
Hung Patrick
0.15 Logic BOD
0.15 Logic BOD for UAT demo purpose
11/02/01
0.15μm Logic Logic Low Voltage 1P2M 1.2V / 3.3V AL
Hung Patrick
0.18 Logic BOD
0.18 Logic BOD for UAT demo purpose
11/06/01
0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AL

FIG. 4A

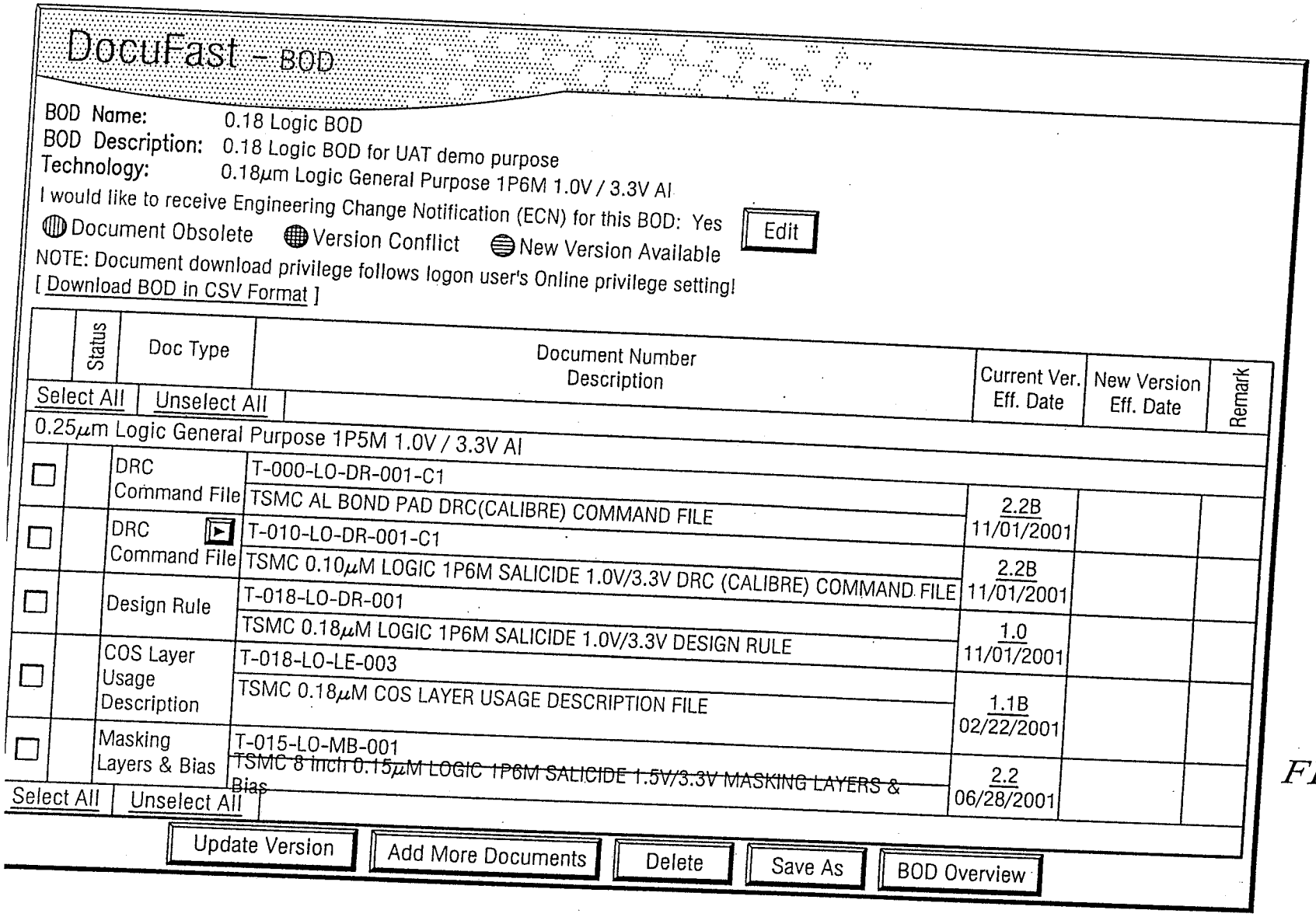

DocuFast – BOD
BOD Name: 0.18 Logic BOD
BOD Description: 0.18 Logic BOD for UAT demo purpose
Technology: 0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AI
I would like to receive Engineering Change Notification (ECN) for this BOD: Yes
Edit
Document Obsolete
Version Conflict
New Version Available
NOTE: Document download privilege follows logon user's Online privilege setting!
[Download BOD in CSV Format]
Status
Doc Type
Document Number
Description
Current Ver. Eff. Date
New Version Eff. Date
Remark
Select All
Unselect All
0.25μm Logic General Purpose 1P5M 1.0V / 3.3V AI
DRC Command File
T-000-LO-DR-001-C1
TSMC AL BOND PAD DRC(CALIBRE) COMMAND FILE
2.2B 11/01/2001
DRC Command File
T-010-LO-DR-001-C1
TSMC 0.10μM LOGIC 1P6M SALICIDE 1.0V/3.3V DRC (CALIBRE) COMMAND FILE
2.2B 11/01/2001
Design Rule
T-018-LO-DR-001
TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V DESIGN RULE
1.0 11/01/2001
COS Layer Usage Description
T-018-LO-LE-003
TSMC 0.18μM COS LAYER USAGE DESCRIPTION FILE
1.1B 02/22/2001
Masking Layers & Bias
T-015-LO-MB-001
TSMC 8 inch 0.15μM LOGIC 1P6M SALICIDE 1.5V/3.3V MASKING LAYERS & Bias
2.2 06/28/2001
Select All
Unselect All
Update Version
Add More Documents
Delete
Save As
BOD Overview

FIG. 4B

DocuFast – Standard BOD

BOD Name: 0.18 Logic BOD
BOD Description: 0.18 Logic BOD for UAT demo purpose
Technology: 0.18μm Logic General Purpose 1P6M 1.8V / 3.3V AL
Please select documents for your own BOD (Bill of Document):
NOTE: 1. Document download privilege follows logon user's Online privilege setting!
2. Obsolete Documents are not included in the standard BOD.
Version Conflict New Version Available

	Status	Doc Type	Document Number Description	Current Ver. Eff. Date	Remark
Select All	Unselect All				
0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AI					
☑		Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001	
		DRC Command File	T-025-LO-DR-001-C1 TSMC AL BOND PAD DA(YCALIBRE) COMMAND FILE	2.2B 11/01/2001	
☑		DRC Command File	T-000-LO-DR-001-M1 BOND PAD DRC (HERCULES) COMMAND FILE	2.1A 03/21/2001	"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision."
	●	Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001	Please contact your account manager for detailed information
		DRC Command File	T-018-LO-DR-001-C1 TSMC 0.18μM LOGIC 1P5M SALICIDE 2.0V/2.5V DRC (CALIBRE) COMMAND FILE	2.2B 04/22/2001	

FIG. 4C-1

TO FIG. 4C-2

FROM FIG. 4C-1

☑		DRC Command File	T-025-LO-DR-001-D1 TSMC 0.18μM LOGIC 2P6M SALICIDE 1.0V/2.2V DRC (DRACULA) COMMAND	2.2A 10/22/2001	"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision."
☐		Qual. Report	T-018-LO-QR-004 TSMC FAB5 0.18μM LOGIC 1P8M SALICIDE 1.8/3.3V QUALIFICATION REPORT	2.0 12/24/2000	
☐		Qual. Report	T-018-LO-QR-003 TSMC FAB-8b 0.18μM LOGIC 1P6M SALICIDE 1.8V/3.3V QUALIFICATION REPORT (GENERIC VERSION)	1.0 08/10/2001	
☐		Qual. Report	WQ-1085-8217 0.18μM LOGIC 1P6M SALICIDE 1.5/3.3V QUALIFICATION REPORT	1.0 03/23/2001	
☐		RC (RC Extraction)	T-018-LO-SP-001-A1 TSMC 0.30μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (ARCADIA) TECH. FILES	1.3A 01/05/2001	
☐		RC (RC Extraction)	T-018-LO-SP-001-B1 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.6V/3.3V RC (STAR-RCXT) TECH. FILES	1.0A 08/28/2000	
☐		RC (RC Extraction)	T-018-LO-SP-001-F1 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (FIRE & ICE) TECH. FILES	1.0A 08/28/2000	
☐		RC (RC Extraction)	T-018-LO-SP-001-H1 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (HYPEREXTRACT) TECH. FILES	1.0A 08/28/2000	
☐		RC (RC Extraction)	T-018-LO-SP-001-Q1 TSMC 0.30μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (COLUMBUS) TECH. FILE(3RD PARTY)	1.00 01/17/2001	*NOTE*

FIG. 4C-2

TO FIG. 4C-3

FROM FIG. 4C-2

☐		RC (RC Extraction)	T-018-LO-SP-001-R1	TSMC 0.30μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (RAPHAEL NES) TECH. FILE	1.4A 07/30/2000	
☐		RC (RC Extraction)	T-018-LO-SP-001-S1	TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (STAR-RC) TECH. FILE	1.0A 01/28/2000	
☐		RC (RC Extraction)	T-018-LO-SP-001-K1	TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V RC (XCALIBRE) TECH. FILE	1.0A 08/08/2001	

Select All | Unselect All

Add to BOD | Cancel

FIG. 4C-3

DocuFast – Standard BOD

BOD Name: 0.18 Logic BOD
BOD Description: 0.18 Logic BOD for UAT demo purpose
Technology: 0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AL
I would like to receive Engineering Change Notification (ECN) for this BOD: Yes [Edit]

Document Obsolete Version Conflict New Version Available
NOTE: Document download privilege follows logon user's Online privilege setting!
[Download BOD in CSV Format]

Select All | Unselect All

	Status	Doc Type	Document Number Description	Current Ver. Eff. Date	New Version Eff. Date	Remark
0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AI						
☐		Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001		
☐		DRC Command File	T-000-LO-DR-001-C1 TSMC AL BOND PAD DRC(CALIBRE) COMMAND FILE	2.2B 11/01/2001		
☑		DRC Command File	T-000-LO-DR-001-H3 BOND PAD DRC (HERCULES) COMMAND FILE	2.3A 03/21/2001		"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision."
	●	Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001		Please contact your account manager for detailed information
☐		DRC Command File	T-018-LO-DR-001-C1 TSMC 0.18μM LOGIC 1P5M SALICIDE 1.0V/3.2V DRC (CALIBRE) COMMAND FILE	2.3A 11/01/2001		

FIG. 4D-1

TO FIG. 4D-2

FROM FIG. 4D-1

☑		DRC Command File	T-000-LO-DR-001-N2 BOND PAD DRC (HERCULES) COMMAND FILE	2.1A 05/23/2001		"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision."
		Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001		Please contact your account manager for detailed information
☐		DRC Command File	T-018-LO-DR-001-C1 TSMC 0.18μM LOGIC 1P5M SALICIDE 1.0V/3.3V DRC (CALIBRE) COMMAND FILE	2.2A 11/01/2001		
☐		DRC Command File	Y-018-LO-DR-001-D2 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0/3.3V DRC (DRACULA) COMMAND	2.2A 10/22/2001		"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision."
		Design Rule	T-018-LO-DR-001 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V DESIGN RULE	2.1 11/06/2001		Please contact your account manager for detailed information
☐		Design Rule	T-018-LO-DR-001 TSMC 0.18μM LOGIC 1P5M SALICIDE 1.0V/3.3V DESIGN RULE	2.0 11/06/2001		
☐		COS Layer Usage Description	T-018-LO-L1-003 TSMC 0.18μM COS LAYER USAGE DESCRIPTION FILE	1.1A 02/22/2001		
☐		Masking Layers & Bias	T-018-LO-M6-001 TSMC 8 inch 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V MASKING LAYERS & BIAS	2.2 04/26/2001		

Select All | Unselect All

Update Version | Add More Documents | Delete | Save As | BOD Overview

16/26

FIG. 4D-2

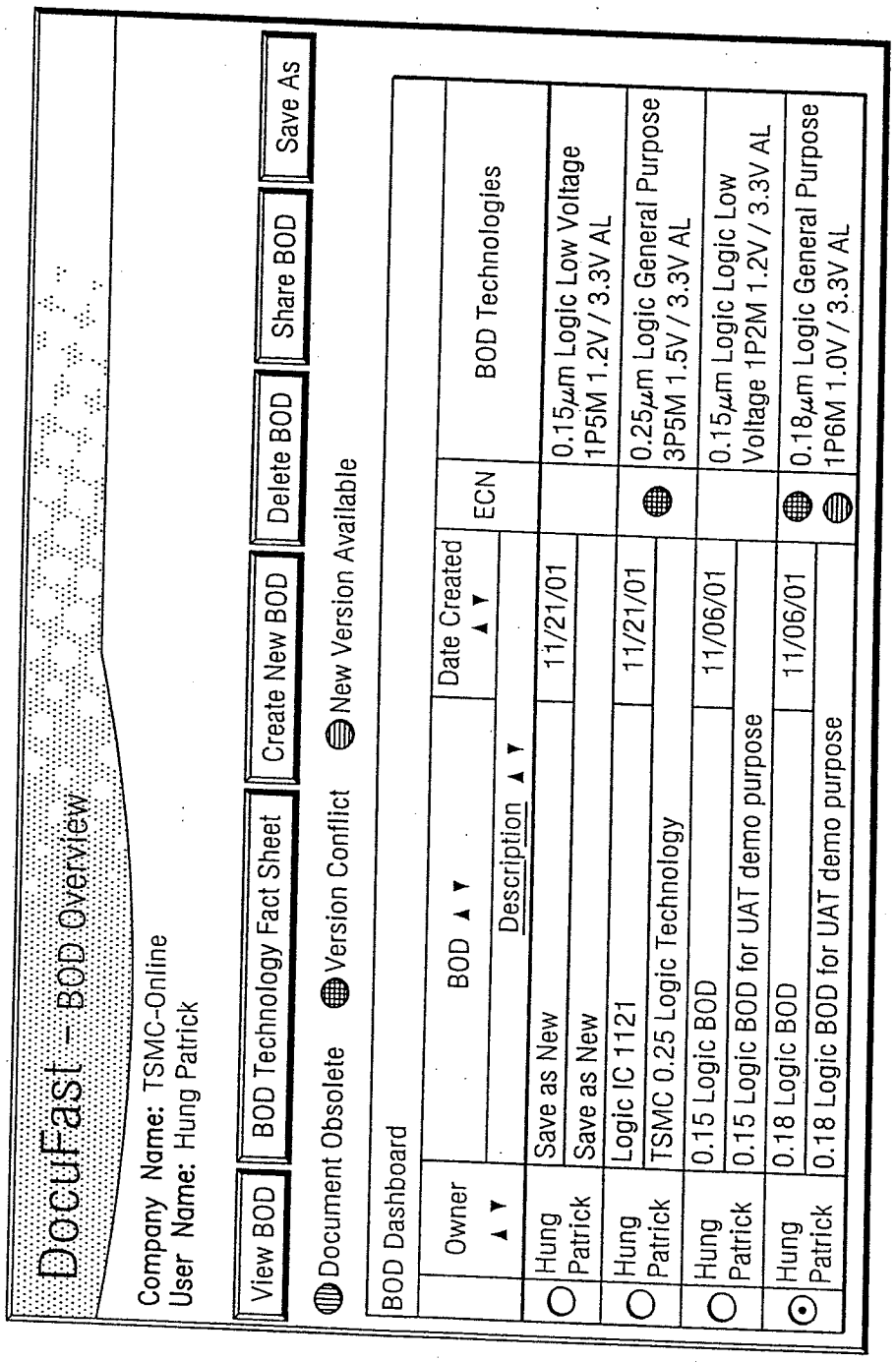

DocuFast - BOD Overview
Company Name: TSMC-Online
User Name: Hung Patrick
View BOD
BOD Technology Fact Sheet
Create New BOD
Delete BOD
Share BOD
Save As
Document Obsolete
Version Conflict
New Version Available
BOD Dashboard
Owner
BOD
Description
Date Created
ECN
BOD Technologies
Hung Patrick
Save as New
11/21/01
0.15μm Logic Low Voltage 1P5M 1.2V / 3.3V AL
Hung Patrick
Save as New
Logic IC 1121
11/21/01
0.25μm Logic General Purpose 3P5M 1.5V / 3.3V AL
Hung Patrick
TSMC 0.25 Logic Technology
Hung Patrick
0.15 Logic BOD
11/06/01
0.15μm Logic Logic Low Voltage 1P2M 1.2V / 3.3V AL
Hung Patrick
0.15 Logic BOD for UAT demo purpose
Hung Patrick
0.18 Logic BOD
11/06/01
0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AL
Hung Patrick
0.18 Logic BOD for UAT demo purpose

FIG. 5A

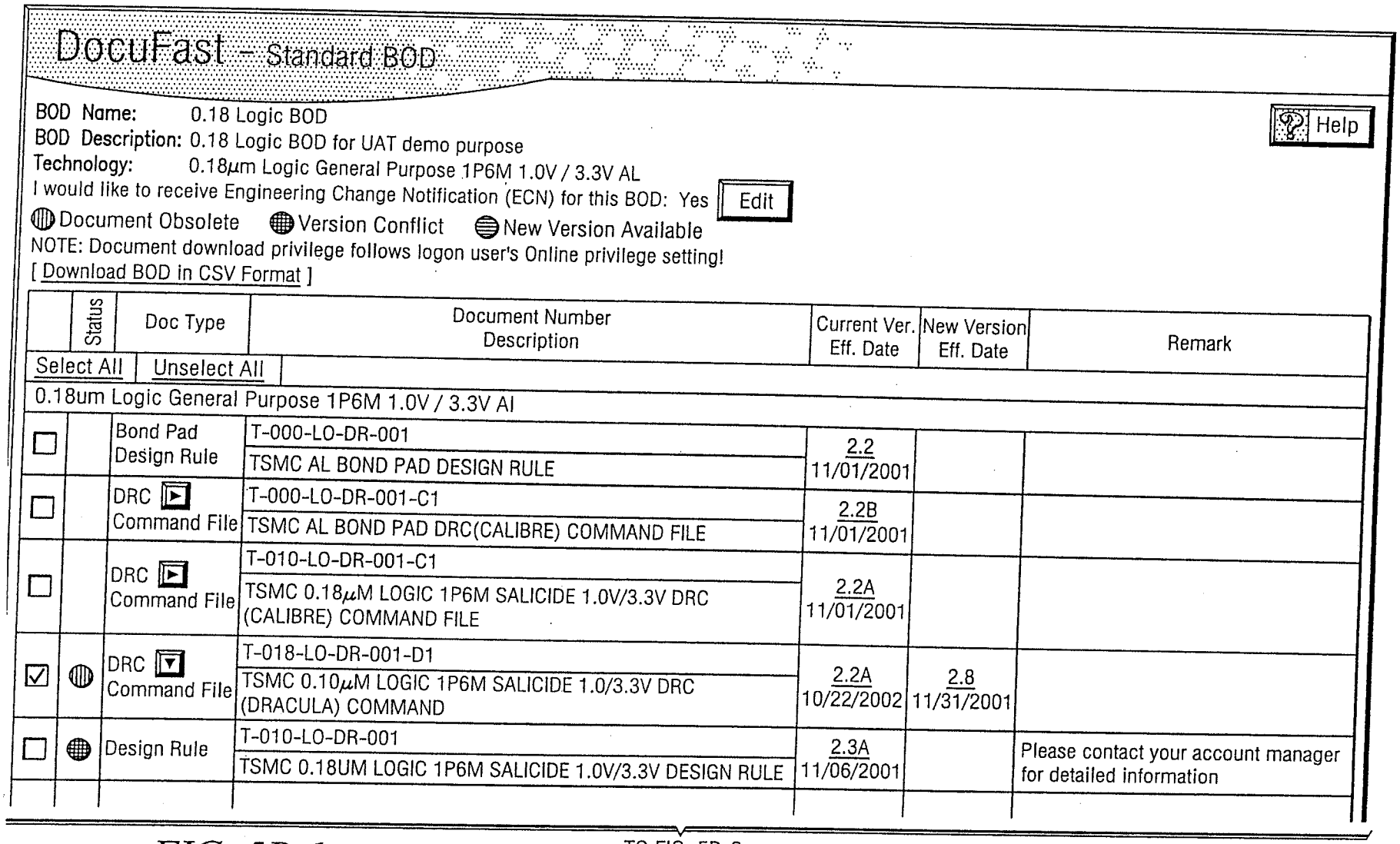


FIG. 5B-1

TO FIG. 5B-2

FROM FIG. 5B-1

☐		Design Rule	T-018-LO-DR-001 TSMC 0.18μM LOGIC 1P5M SALICIDE 1.0V/3.3V DESIGN RULE	2.0 11/06/2001			
☐		COS Layer Usage Description	T-018-LO-L1-003 TSMC 0.18μM COS LAYER USAGE DESCRIPTION FILE	1.1A 02/22/2001			
☐		Masking Layers & Bias	T-018-LO-M6-001 TSMC 8 inch 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V MASKING LAYERS & BIAS	2.2 04/28/2001			

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FIG. 5B-2

BOD Name: 0.18 Logic BOD
BOD Description: 0.18 Logic BOD for UAT demo purpose
Technology: 0.18μm Logic General Purpose 1P6M 1.0V / 3.3V AL
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	Status	Doc Type	Document Number Description	Current Ver. Eff. Date	New Version Eff. Date	Remark
Select All | Unselect All						
0.18μm Logic General Purpose 1P6M 1.0V / 3.3V Al						
☐		Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/01/2001		
☐		DRC Command File	T-000-LO-DR-001-C1 TSMC AL BOND PAD DRC(CALIBRE) COMMAND FILE	2.2B 11/01/2001		
☐		DRC Command File	T-018-LO-DR-001-C1 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V DRC (CALIBRE) COMMAND FILE	2.2A 11/01/2001		
☐		DRC Command File	T-018-LO-DR-001-D1 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0/3.3V DRC (DRACULA) COMMAND	2.2 11/21/2001		
☐		Design Rule	T-018-LO-DR-001 TSMC 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V DESIGN RULE	2.3 11/04/2001		

FIG. 5C-1

TO FIG. 5C-2

FROM FIG. 5C-1

☑		COS Layer Usage Description	T-018-LO-L1-003 TSMC 0.18μM COS LAYER USAGE DESCRIPTION FILE	1.1A 02/22/2001			OBSOLETE (11/21/2001)
☐		Masking Layers & Bias	T-018-LO-M6-001 TSMC 8 inch 0.18μM LOGIC 1P6M SALICIDE 1.0V/3.3V MASKING LAYERS & BIAS	2.2 06/20/2001			

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FIG. 5C-2

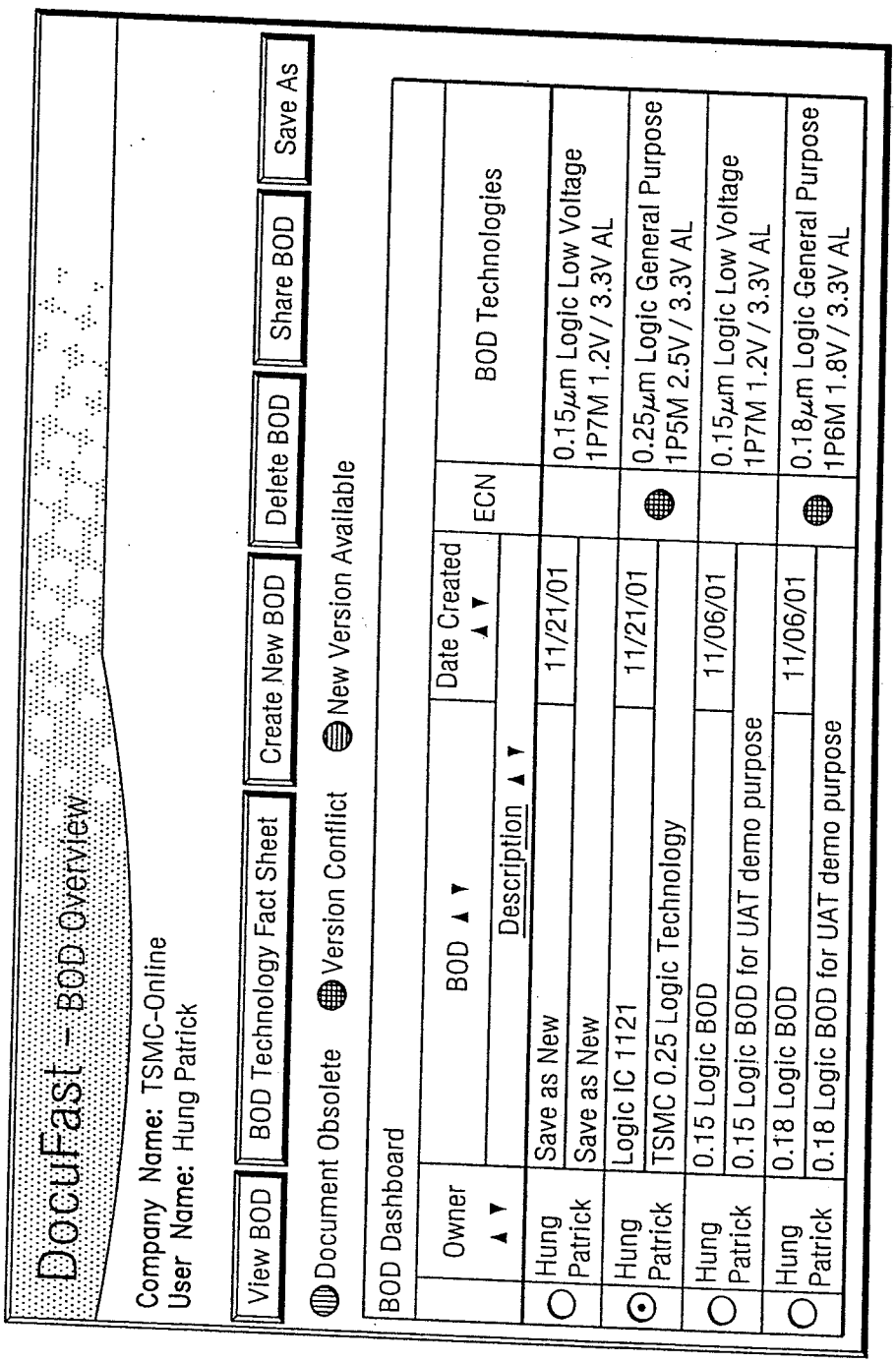

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BOD Technologies
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11/21/01
0.15μm Logic Low Voltage 1P7M 1.2V / 3.3V AL
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Save as New
Logic IC 1121
TSMC 0.25 Logic Technology
11/21/01
0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AL
Hung Patrick
0.15 Logic BOD
0.15 Logic BOD for UAT demo purpose
11/06/01
0.15μm Logic Low Voltage 1P7M 1.2V / 3.3V AL
Hung Patrick
0.18 Logic BOD
0.18 Logic BOD for UAT demo purpose
11/06/01
0.18μm Logic General Purpose 1P6M 1.8V / 3.3V AL

FIG. 6A

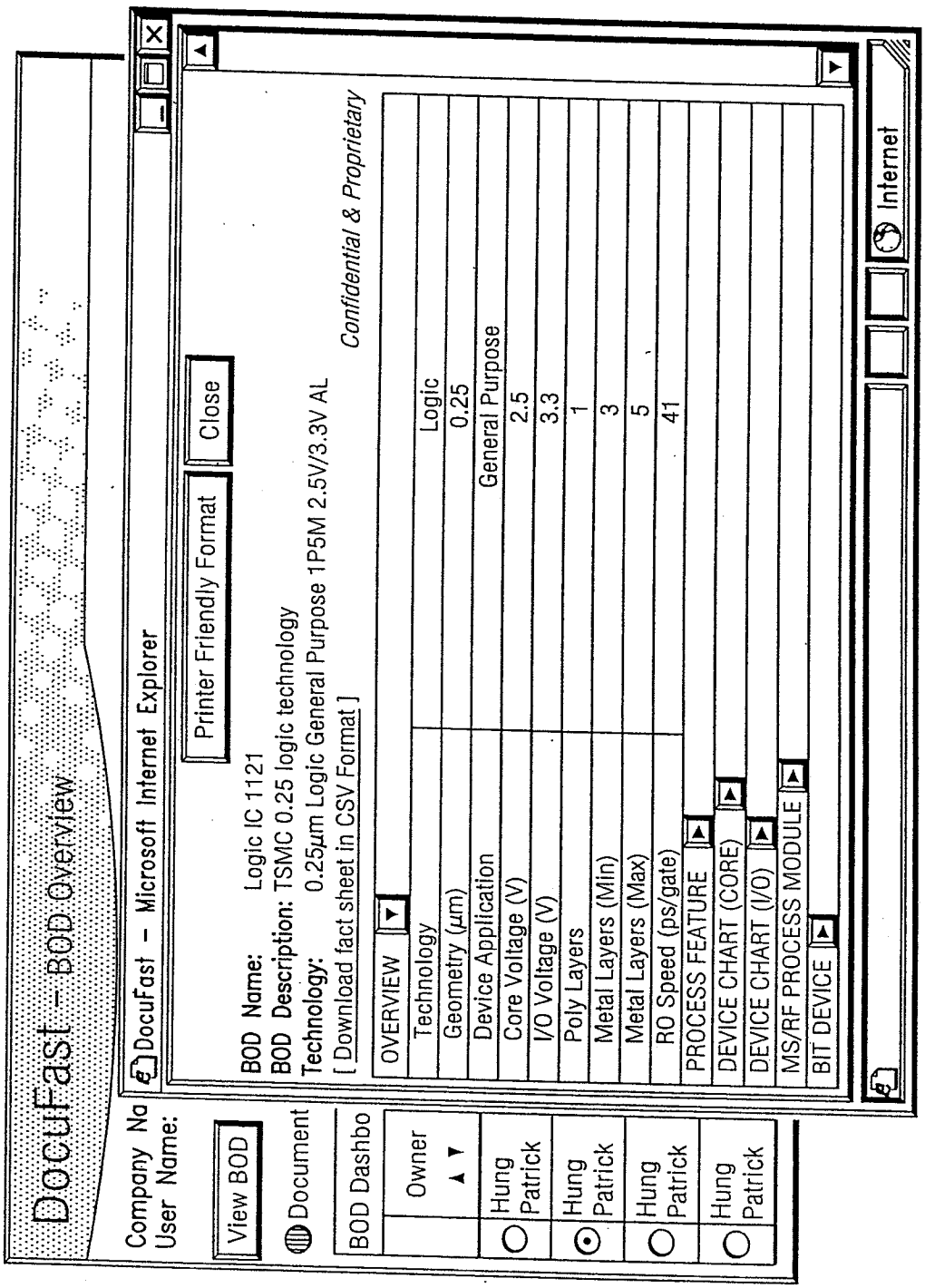

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BOD Description: TSMC 0.25 logic technology
Technology: 0.25µm Logic General Purpose 1P5M 2.5V/3.3V AL
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OVERVIEW
Technology Logic
Geometry (µm) 0.25
Device Application General Purpose
Core Voltage (V) 2.5
I/O Voltage (V) 3.3
Poly Layers 1
Metal Layers (Min) 3
Metal Layers (Max) 5
RO Speed (ps/gate) 41
PROCESS FEATURE
DEVICE CHART (CORE)
DEVICE CHART (I/O)
MS/RF PROCESS MODULE
BIT DEVICE
Internet

FIG. 6B

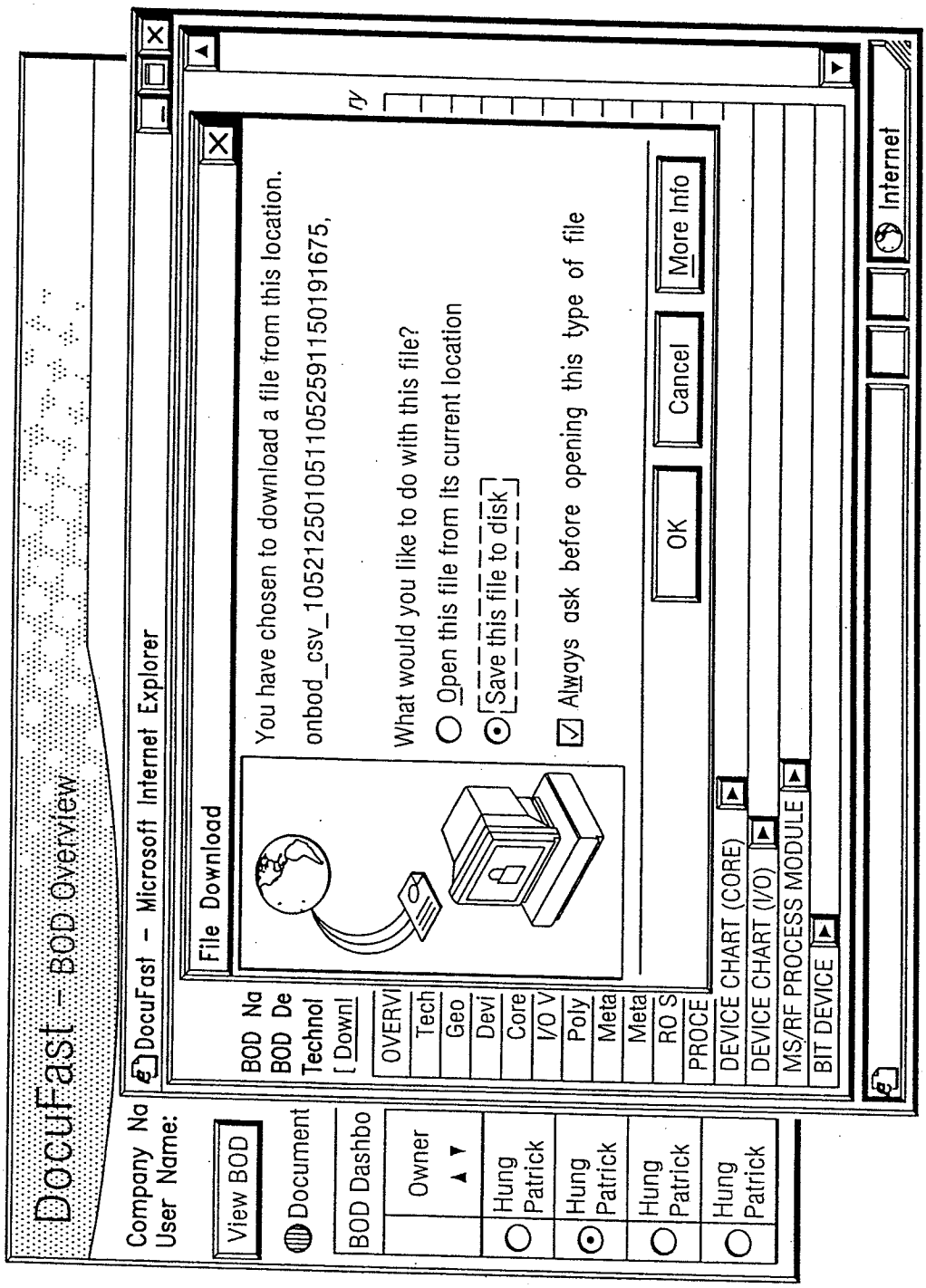

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Cancel
More Info
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DEVICE CHART (I/O)
MS/RF PROCESS MODULE
BIT DEVICE
Internet

FIG. 6C

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Help

BOD Name: Logic IC 1121
BOD Description: TSMC 0.25 logic technology
Technology: 0.25μm Logic General Purpose 1P5M 2.5V / 3.3V AL
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	Status	Doc Type	Document Number Description	Current Ver. Eff. Date	New Version Eff. Date	Remark
Select All	Unselect All					
0.25μm Logic General Purpose 1P6M 1.0V / 3.3V AI						
☐		Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/02/2001		
☐		Brief Design Rule	T-025-LO-DR-000 0.25μM LOGIC (1P5M, 2.5V/3.3V) SALICIDE PROCESS BRIEF DESIGN RULE	1.0 12/04/1997		
☐		DRC Command File	T-000-LO-DR-001-M1 BOND PAD DRC (HERCULES) COMMAND FILE	2.1A 01/13/2001		"This is not the most updated version. Please contact your TSMC account manager for the availability of the most updated revision"
☐	●	Bond Pad Design Rule	T-000-LO-DR-001 TSMC AL BOND PAD DESIGN RULE	2.2 11/02/2001		Please contact your account manager for detailed information
☐		DRC Command File	T-025-LO-DR-001-C1 TSMC 0.25μM LOGIC 1P5M SALICIDE 2.5V/3.3V DRC (CALIBRE) COMMAND FILE	2.0B 06/15/2001		

FIG. 7A

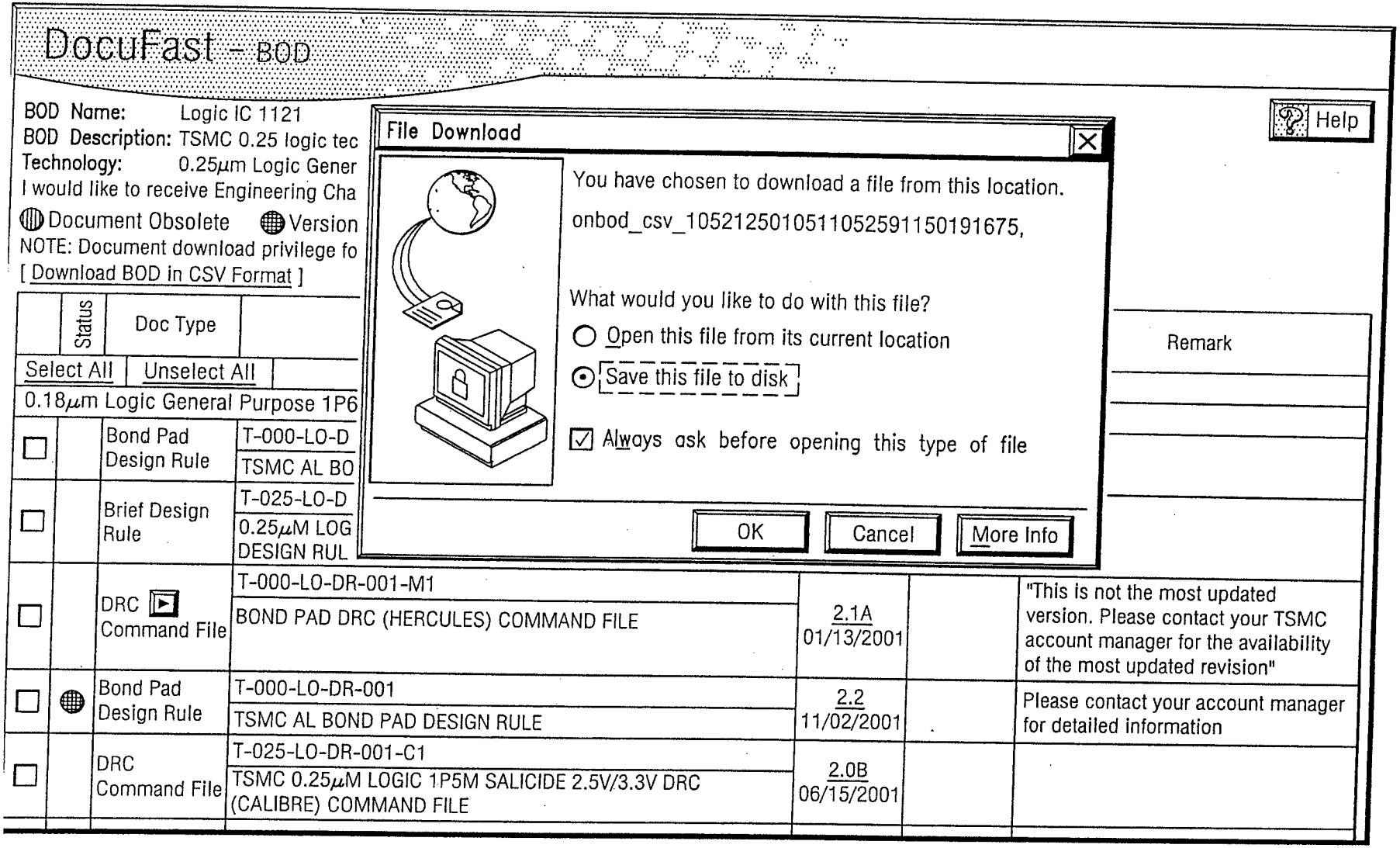

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Technology: 0.25μm Logic Gener
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0.18μm Logic General Purpose 1P6
Bond Pad Design Rule
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TSMC AL BO
Brief Design Rule
T-025-LO-D
0.25μM LOG DESIGN RUL
DRC Command File
T-000-LO-DR-001-M1
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Bond Pad Design Rule
T-000-LO-DR-001
TSMC AL BOND PAD DESIGN RULE
2.2
11/02/2001
Please contact your account manager for detailed information
DRC Command File
T-025-LO-DR-001-C1
TSMC 0.25μM LOGIC 1P5M SALICIDE 2.5V/3.3V DRC (CALIBRE) COMMAND FILE
2.0B
06/15/2001

FIG. 7B